

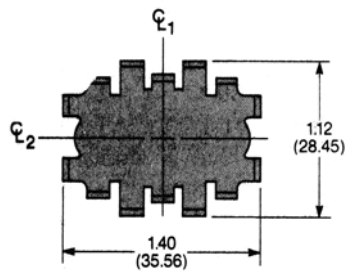
### METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LB66B1

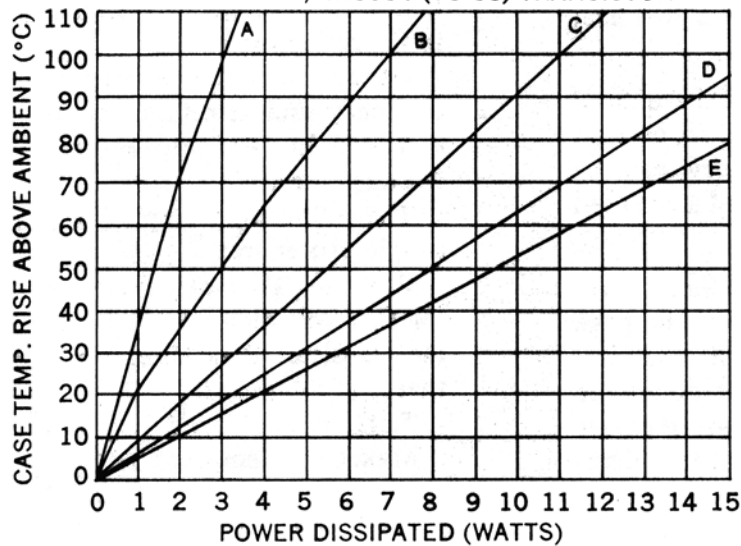
Natural Conv. ( $^{\circ}\text{C}/\text{W}$ ): 17.1

Forced Air ( $^{\circ}\text{C}/\text{W}$ ): 5.3

Mounting Envelope: 1.40" x 1.12" x .50"



LB66B1CB w/2N3054 (TO-66) TRANSISTOR



#### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

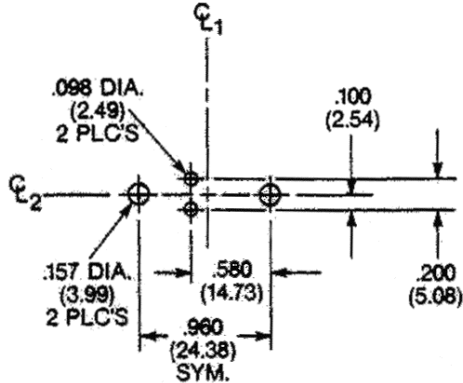
- Thermal Resistance Case to Sink is 0.5-0.7  $^{\circ}\text{C}/\text{W}$  w/Joint Compound.
- Derate 1.4  $^{\circ}\text{C}/\text{watt}$  for unplated part in natural convection only.

## Ordering Information

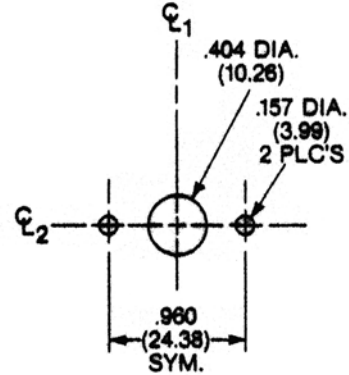
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
LB66B1-76U	LB66B1-76CB	LB66B1-76B	Undrilled	--	6.2
LB66B1U	LB66B1CB	LB66B1B	TO-66	9	6.2
LB66B1-67U	LB66B1-67CB	LB66B1-67B	TO-66 IC	7	6.2
LB66B1-77U	LB66B1-77CB	LB66B1-77B	TO-66 IC (Socket)	10	6.2

### HOLE PATTERNS

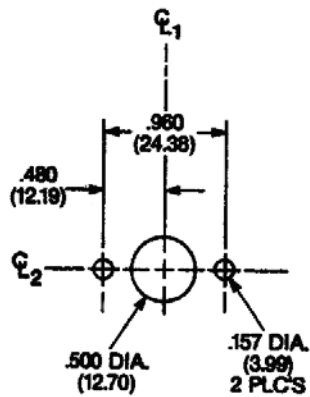
9. Hole Pattern no. 133 accommodates TO-66s. Available in LB series heat dissipators only.



7. Hole pattern no. 191 accommodates To-66 lcs. Available in LA-A, LA-B, and LB series heat dissipators only.



10. Hole pattern no. 225 accommodates TO-66 ICs (socket). Available in LB series heat dissipators only.



### CTS IERC, Heat Sinks and Thermal Management Solutions

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